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To the Honorable Commissioner of F.
Please record the attached original documents or copy thereof.

1-4

1. Name of conveying party(ies):

Taek-seon Park; and
Sung-min Yim

Additional name(s) of conveying party(ies) attached?
 YES NO

2. Name and address of receiving party(ies):
Name:

Samsung Electronics Co., Ltd.

Internal Address:

Street Address:
San #16 Banwol-Ri, Taeon-Eup

City: Hwasung-City

State: Gyeonggi-Do

Country/Zip: KOREA 445-701

Additional name(s) & address(es) attached?
 YES NO

3. Nature of conveyance:

 Assignment Merger

 Security Agreement Change of Name

 Other _____

Execution Date: December 20, 2007

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: December 20, 2007

A. Patent Application No.(s):
(include series code or filing date)

B. Patent No.(s):

Additional application or patent numbers attached? YES NO

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Monica H. Choi
Law Office of Monica H. Choi
Address: P.O. Box 3424
City: Dublin
State: Ohio Zip: 43016-0204

6. Total number of applications and patents involved: 1


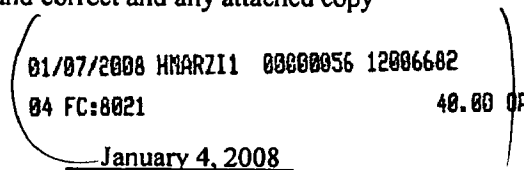
7. Total Fee (37 CFR 3.41) \$ 40.00
 Enclosed Authorized to charge Deposit Account 50-1178

8. Should any fee adjustment be necessary to effect proper recordation, please debit or credit our Deposit Account No. _____, as necessary.

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Monica H. Choi, Reg. No. 41,671
Name of Person Signing  Signature  January 4, 2008
Date

Atty. Docket No.: S07-37

Total number of pages including cover sheet, attachments and document: Three (3)

ASSIGNMENT

Inventor(s): **TAEK-SEON PARK ET AL.**
Date of Execution
of Application: _____

Serial No.: _____
Filing Date: _____

In consideration of One Dollar (\$1.00) and other good and valuable considerations in hand paid, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to:

SAMSUNG ELECTRONICS CO., LTD,
a corporation having a primary place of business in
Suwon-si, Gyeonggi-do, Republic of Korea

its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled:

DATA OUTPUT CIRCUIT IN SEMICONDUCTOR MEMORY DEVICE

and identified as: _____
Serial No.: _____
Case No. **S07-37**
Filing Date: _____

in the Law Office of Monica H. Choi and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension of such patents, and further assigns to said assignees the priority right provided by the International Convention.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignees.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known, and the date of execution of the application.

The undersigned warrants himself to be the owner of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

For said considerations the undersigned hereby agrees, upon the request and at the expense of said assignees, its successors and assigns, to execute any and all divisional, continuation and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignees, its successors or assigns may deem necessary or expedient, and for the said considerations the undersigned authorize said assignees to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further

agree, upon the request of said assignees, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignees, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence, and performing any and all other acts necessary to obtain, maintain and enforce said Letters Patent, both United States and foreign, and vests all rights therein hereby conveyed in the assignees, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignees, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made.

Taek Seon Park
TAEK-SEON PARK

Dec. 20. 2007
DATE

Sung min Yim
SUNG-MIN YIM

Dec. 20. 2007
DATE